

Notice of References Cited	Application/Control No. 10/568,077		Applicant(s)/Patent Under Reexamination SMALL ET AL.	
	Examiner STEPHANIE DUCLAIR		Art Unit 4171	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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*	B	US-2003/0119319	06-2003	Sinha et al.	438/691
*	C	US-6,316,365	11-2001	Wang et al.	438/692
*	D	US-6,355,075	03-2002	Ina et al.	51/308
*	E	US-6,043,159	03-2000	Jacquinot et al.	438/693
*	F	US-6,746,498	06-2004	Buehler, Mark F.	51/308
*	G	US-6,261,967	07-2001	Athavale et al.	438/717
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.